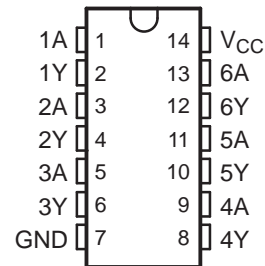


HEX INVERTER

FEATURES

- Qualified for Automotive Applications
- 2-V to 5.5-V V_{CC} Operation
- Unbuffered Outputs
- Typical V_{OLP} (Output Ground Bounce)
 $<0.8\text{ V}$ at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$
- Typical V_{OHV} (Output V_{OH} Undershoot)
 $>2.3\text{ V}$ at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$
- Supports Mixed-Mode Voltage Operation on All Ports

**PW PACKAGE
(TOP VIEW)**



DESCRIPTION/ORDERING INFORMATION

This hex inverter is designed for 2-V to 5.5-V V_{CC} operation.

The SN74LVU04A-Q1 contains six independent inverters with unbuffered outputs. This device performs the Boolean function $Y = \bar{A}$.

ORDERING INFORMATION⁽¹⁾

T_A	PACKAGE ⁽²⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	TSSOP – PW	Reel of 2000	SN74LVU04AQPWRQ1	LU04AQ

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

FUNCTION TABLE (EACH INVERTER)

INPUT A	OUTPUT Y
H	L
L	H

LOGIC DIAGRAM, EACH INVERTER (POSITIVE LOGIC)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	−0.5	7	V
V_I	Input voltage range ⁽²⁾	−0.5	7	V
V_O	Output voltage range ^{(2) (3)}	−0.5	$V_{CC} + 0.5$	V
I_{IK}	Input clamp current	$V_I < 0$		−20 mA
I_{OK}	Output clamp current	$V_O < 0$		−50 mA
I_O	Continuous output current	$V_O = 0$ to V_{CC}		±25 mA
	Continuous current through V_{CC} or GND			±50 mA
θ_{JA}	Package thermal impedance ⁽⁴⁾			113 °C/W
ESD rating ⁽⁵⁾	Human-Body Model		1.5 (H1C)	kV
	Charged-Device Model		1 (C5)	
	Machine Model		200 (M3)	V
T_{stg}	Storage temperature range	−65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 5.5 V maximum.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.
- (5) ESD protection level per AEC Q100 classification

Recommended Operating Conditions⁽¹⁾

		MIN	MAX	UNIT
V_{CC}	Supply voltage	2	5.5	V
V_{IH}	High-level input voltage	$V_{CC} = 2$ V	1.7	V
		$V_{CC} = 2.3$ V to 2.7 V	$V_{CC} \times 0.8$	
		$V_{CC} = 3$ V to 3.6 V	$V_{CC} \times 0.8$	
		$V_{CC} = 4.5$ V to 5.5 V	$V_{CC} \times 0.8$	
V_{IL}	Low-level input voltage	$V_{CC} = 2$ V	0.3	V
		$V_{CC} = 2.3$ V to 2.7 V	$V_{CC} \times 0.2$	
		$V_{CC} = 3$ V to 3.6 V	$V_{CC} \times 0.2$	
		$V_{CC} = 4.5$ V to 5.5 V	0.8	
V_I	Input voltage	0	5.5	V
V_O	Output voltage	0	V_{CC}	V
I_{OH}	High-level output current	$V_{CC} = 2$ V	−50	μA
		$V_{CC} = 2.3$ V to 2.7 V	−2	mA
		$V_{CC} = 3$ V to 3.6 V	−6	
		$V_{CC} = 4.5$ V to 5.5 V	−12	
I_{OL}	Low-level output current	$V_{CC} = 2$ V	50	μA
		$V_{CC} = 2.3$ V to 2.7 V	2	mA
		$V_{CC} = 3$ V to 3.6 V	6	
		$V_{CC} = 4.5$ V to 5.5 V	12	
T_A	Operating free-air temperature	−40	125	°C

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V _{CC}	–40°C to 125°C			–40°C to 85°C			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
V _{OH}	I _{OH} = –50 μA	V _{IL} = 0 V	2 V to 5.5 V	V _{CC} – 0.1			V _{CC} – 0.1			V
	I _{OH} = –2 mA		2			2				
	I _{OH} = –6 mA		2.48			2.48				
	I _{OH} = –12 mA		3.7			3.8				
V _{OL}	I _{OL} = 50 μA	V _{IH} = V _{CC}	2 V to 5.5 V	0.1			0.1			V
	I _{OL} = 2 mA		0.4			0.4				
	I _{OL} = 6 mA		0.44			0.44				
	I _{OL} = 12 mA		0.55			0.55				
I _I	V _I = 5.5 V or GND		0 V to 5.5 V	±1			±1			μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0		5.5 V	20			20			μA
C _i	V _I = V _{CC} or GND		3.3 V	4			4			pF

Switching Characteristics

over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C			–40°C to 125°C		–40°C to 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A	Y	C _L = 50 pF		4.7	11.4	1	16	1	13	ns

Switching Characteristics

over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C			–40°C to 125°C		–40°C to 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A	Y	C _L = 50 pF		3.9	7	1	11	1	8	ns

Noise Characteristics

V_{CC} = 3.3 V, C_L = 50 pF, T_A = 25°C⁽¹⁾

PARAMETER		MIN	TYP	MAX	UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.5	0.8	V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		–0.1	–0.8	V
V _{OH(V)}	Quiet output, minimum dynamic V _{OH}		3		V
V _{IH(D)}	High-level dynamic input voltage		2.31		V
V _{IL(D)}	Low-level dynamic input voltage			0.99	V

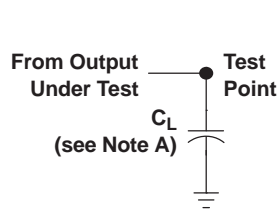
(1) Characteristics are for surface-mount packages only.

Operating Characteristics

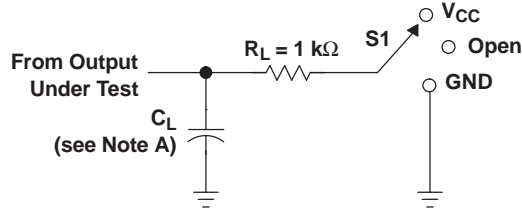
T_A = 25°C

PARAMETER		TEST CONDITIONS		V _{CC}	TYP	UNIT
C _{pd}	Power dissipation capacitance	C _L = 50 pF, f = 10 MHz		3.3 V	5.6	pF
				5 V	6.7	

PARAMETER MEASUREMENT INFORMATION

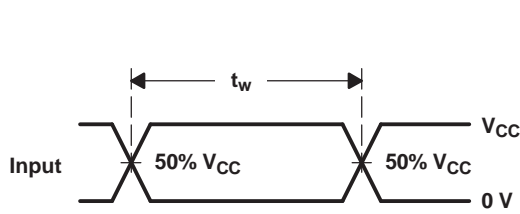


**LOAD CIRCUIT FOR
TOTEM-POLE OUTPUTS**

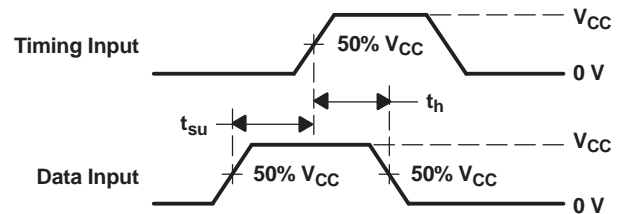


**LOAD CIRCUIT FOR
3-STATE AND OPEN-DRAIN OUTPUTS**

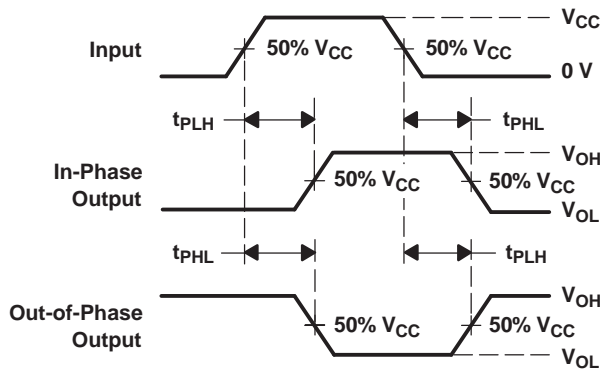
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{CC}
t_{PHZ}/t_{PZH}	GND
Open Drain	V_{CC}



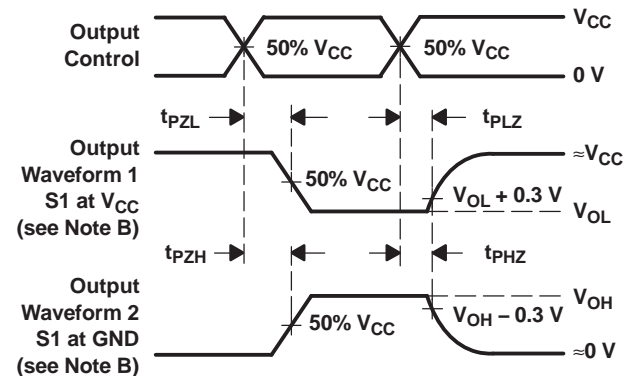
**VOLTAGE WAVEFORMS
PULSE DURATION**



**VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES**



**VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS**



**VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING**

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 3 \text{ ns}$, $t_f \leq 3 \text{ ns}$.
 - D. The outputs are measured one at a time, with one input transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PHL} and t_{PLH} are the same as t_{pd} .
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN74LVU04AQPWRG4Q1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LU04AQ	Samples
SN74LVU04AQPWRQ1	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI	-40 to 125	LU04AQ	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

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OTHER QUALIFIED VERSIONS OF SN74LVU04A-Q1 :

- Catalog: [SN74LVU04A](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVU04AQPWRG4Q 1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

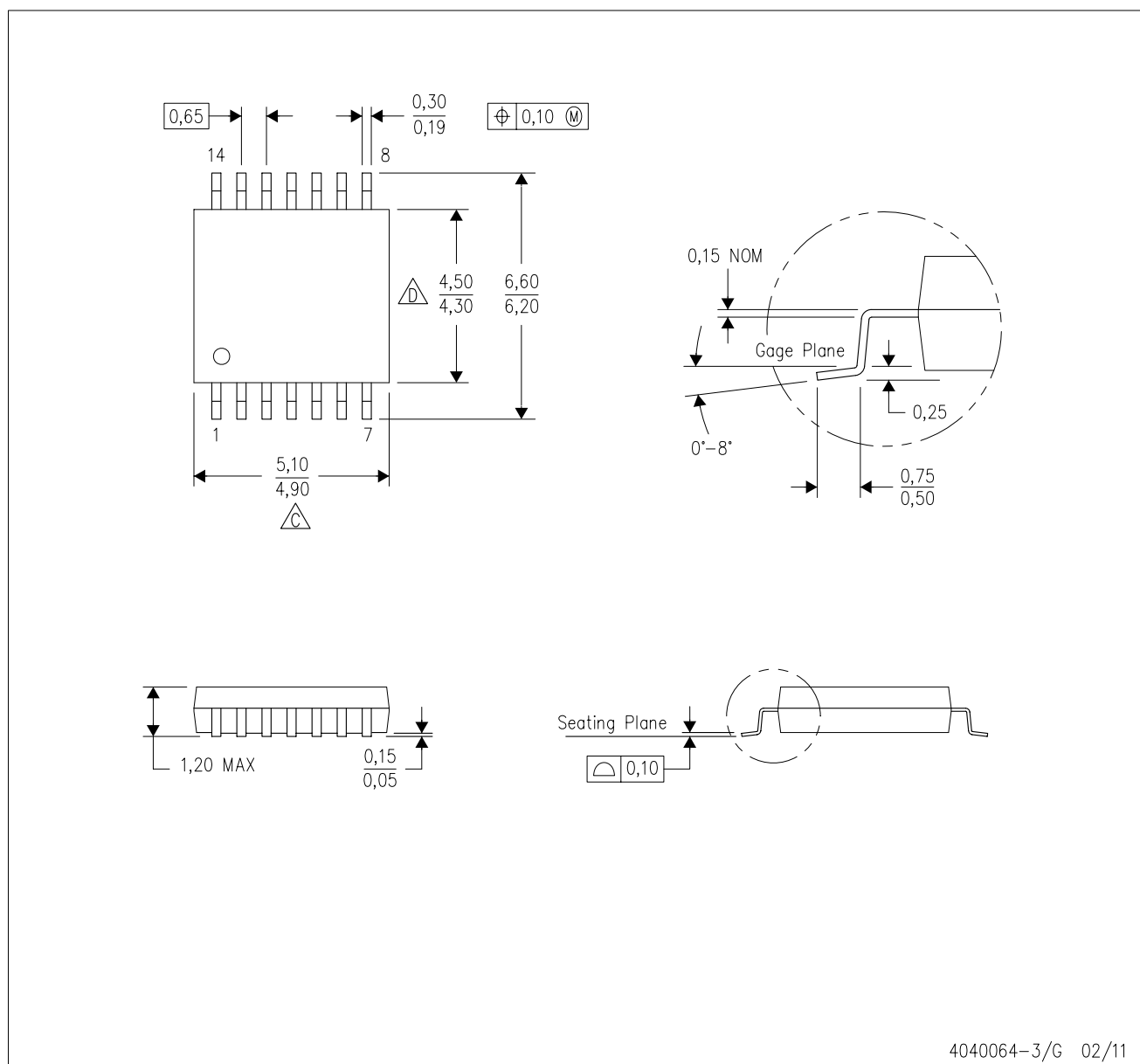


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVU04AQPWRG4Q1	TSSOP	PW	14	2000	367.0	367.0	35.0

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4040064-3/G 02/11

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4211284-2/F 12/12

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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